Replace the paragraph beginning at page 1, line 16, with:

Fig. 7 is a view showing a connection between a conventional TV signal processing IC and a microcomputer. A signal processing IC 71 is a semiconductor device having the ability to process TV signals. An MCU 72 is a semiconductor device which functions as a microcomputer for the control and tuning of the signal processing IC 71.

Replace the paragraph beginning at page 2, line 15, with:

The signal processing IC 71 and the MCU 72 are mounted on a substrate and each terminal of the signal processing IC 71 and the MCU 72 is connected by wiring printed on the substrate.

Replace the paragraph beginning at page 2, line 22, with:

However, in the conventional television receiver, terminals which connect the signal processing IC with the MCU are scattered on each side, bringing about complicated connections and making the wiring region of a printed substrate large, giving rise to the problem of a larger packaging area of the substrate.

Replace the paragraph beginning at page 3, line 3, with:

Also, the signal processing IC requires the crystal oscillator for processing color signals and the MCU requires the oscillator for a system clock, posing the problem that parts having similar functions are required and the number of parts is increased.

Replace the paragraph beginning at page 3, line 8, with:

Besides television receivers, in all semiconductor integrated devices including a plurality of semiconductor devices, each semiconductor device is provided with connecting terminals without considering positional relationships with other semiconductor devices. Accordingly, there is a problem that the wiring region of a substrate is increased and therefore the packaging area of the substrate is increased. Further, a separate oscillator is provided for each semiconductor device. Accordingly, the number of parts and, therefore, the packaging area increases.

Replace the paragraph beginning at page 3, line 21, with:

It is an object of the present invention to provide an inexpensive semiconductor integrated device in which it is possible to reduce the wiring region on the substrate and also reduce the number of parts and thereby decrease the packaging area.

Replace the paragraph beginning at page 5, line 2, with:

Fig. 2 is a view showing the function of each of a crystal oscillator, a signal processing IC, and an MCU shown in Fig. 1.

Replace the paragraph beginning at page 5, line 5, with:

Fig. 3 is a view showing a structure when the number of terminals connected from a signal processing IC to an MCU exceeds the number of the terminals which can be disposed on one side.